AO7400/MC7400

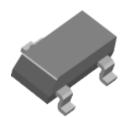
Freescale

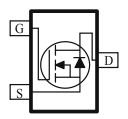
N-Channel 20V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

PRODUCT SUMMARY			
V _{DS} (V)	$_{\rm S}$ (V) $r_{\rm DS(on)}$ (Ω) $I_{\rm D}$ (A		
20	$0.058@V_{CS}=4.5V$	2.0	
20	$0.082 @V_{CS} = 2.5V$	1.7	

- Low r_{DS(on)} provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SC70-3 saves board space
- Fast switching speed
- High performance trench technology





ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C UNLESS OTHERWISE NOTED)					
Parameter			Maximum	Units	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		Vas	±8	v	
Continuous Drain Current ^a	$T_A=25^{\circ}C$	I.	2.0		
	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	цD	1.7	А	
Pulsed Drain Current ^b		I _{DM}	±20		
Continuous Source Current (Diode Conduction) ^a		Is	1.6	Α	
	$T_A=25^{\circ}C$	D	0.34	w	
Power Dissipation ^a	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	I D	0.22	vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Ambient ^a	t <= 5 sec	D	100	°C/W	
	Steady-State	R _{THJA}	166		

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. Pulse width limited by maximum junction temperature

SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)							
Parameter	Sh al	Test Conditions	Limits			TL	
	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \text{ uA}$	0.7			V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			±100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 16 V, V_{GS} = 0 V$ $V_{DS} = 16 V, V_{GS} = 0 V, T_J = 55^{\circ}C$			1	uA	
On-State Drain Current ^A	I _{D(on)}	$V_{\rm DS} = 5 \text{ V}, \text{ V}_{\rm GS} = 4.5 \text{ V}$	10		10	А	
		$V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$			58	mΩ	
Drain-Source On-Resistance ^A	r _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 1.7 \text{ A}$			82		
Forward Tranconductance ^A	g_{fs}	$V_{\rm DS} = 10$ V, $I_{\rm D} = 2.0$ A		11.3		S	
Diode Forward Voltage	V _{SD}	$I_{\rm S} = 1.6 \text{ A}, V_{\rm GS} = 0 \text{ V}$		0.75		V	
Dynamic ^b		-					
Total Gate Charge	Qg			7.5			
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 2.0 \text{ A}$		0.6		nC	
Gate-Drain Charge	Q _{gd}	1 F		1.0			
Input Capacitance	C _{iss}			720			
Output Capacitance	C _{oss}	$V_{\rm DS} = 15 \text{ V}, V_{\rm GS} = 0 \text{ V},$		165		pF	
Reverse Transfer Capacitance	C _{rss}	f = 1MHz		60			
Turn-On Delay Time	t _{d(on)}			8			
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 15 \Omega, I_D = 1 \text{ A},$		24		na	
Turn-Off Delay Time	t _{d(off)}	$V_{GEN} = 4.5 V$		35		ns	
Fall-Time	t _f			10]	

Notes

a. Pulse test: $PW \le 300$ us duty cycle $\le 2\%$.

b. Guaranteed by design, not subject to production testing.

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Typical Electrical Characteristics (N-Channel)

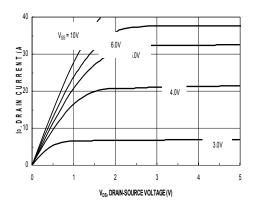


Figure 1. On-Region Characteristics

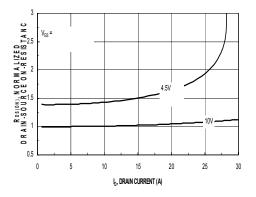


Figure 3. On Resistance Vs Vgs Voltage

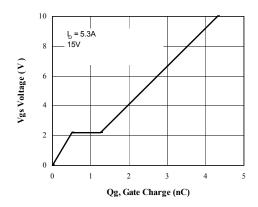


Figure 5. Gate Charge Characteristics

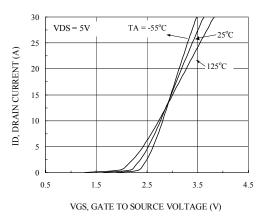


Figure 2. Body Diode Forward Voltage Variation

with Source Current and Temperature

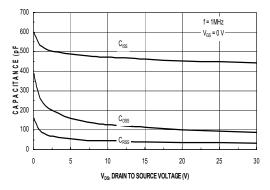


Figure 4. Capacitance Characteristics

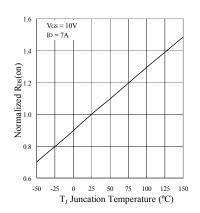


Figure 6. On-Resistance Variation with Temperature

Typical Electrical Characteristics (N-Channel)

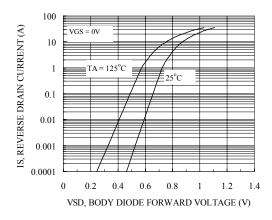


Figure 7. Transfer Characteristics

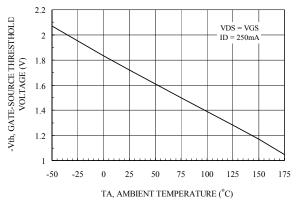


Figure 9. Vth Gate to Source Voltage Vs Temperature

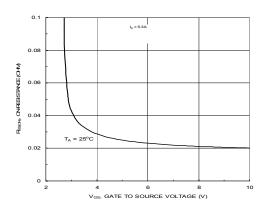


Figure 8. On-Resistance with Gate to Source Voltage

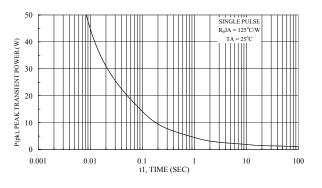
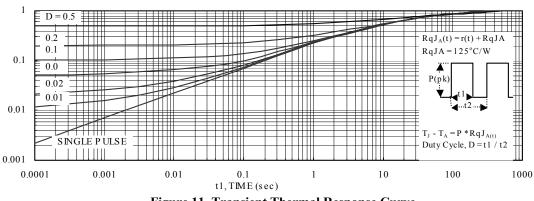


Figure 10. Single Pulse Maximum Power Dissipation



Normalized Thermal Transient Junction to Ambient

